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#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	16MHz
Connectivity	-
Peripherals	LVD, POR, PWM, WDT
Number of I/O	4
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.154", 3.90mm Width)
Supplier Device Package	8-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s08qd4j1msc

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# **MC9S08QD4 Series Features**

## 8-Bit HCS08 Central Processor Unit (CPU)

- 16 MHz HCS08 CPU (central processor unit)
- HC08 instruction set with added BGND instruction
- Background debugging system
- Breakpoint capability to allow single breakpoint setting during in-circuit debugging (plus two more breakpoints in on-chip debug module)
- Support for up to 32 interrupt/reset sources

### Memory

- Flash read/program/erase over full operating voltage and temperature
- Flash size:
  - MC9S08QD4/S9S08QD4: 4096 bytes
  - MC9S08QD2/S9S08QD2: 2048 bytes
- RAM size
  - MC9S08QD4/S9S08QD4: 256 bytes
  - MC9S08QD2/S9S08QD2: 128 bytes

### **Power-Saving Modes**

• Wait plus three stops

### **Clock Source Options**

• ICS — Internal clock source module (ICS) containing a frequency-locked-loop (FLL) controlled by internal. Precision trimming of internal reference allows 0.2% resolution and 2% deviation over temperature and voltage.

### **System Protection**

- Watchdog computer operating properly (COP) reset with option to run from dedicated 32 kHz internal clock source or bus clock
- Low-voltage detection with reset or interrupt
- Illegal opcode detection with reset
- Illegal address detection with reset

Flash block protect

#### Peripherals

- ADC 4-channel, 10-bit analog-to-digital converter with automatic compare function, asynchronous clock source, temperature sensor and internal bandgap reference channel. ADC is hardware triggerable using the RTI counter.
- **TIM1** 2-channel timer/pulse-width modulator; each channel can be used for input capture, output compare, buffered edge-aligned PWM, or buffered center-aligned PWM
- **TIM2** 1-channel timer/pulse-width modulator; each channel can be used for input capture, output compare, buffered edge-aligned PWM, or buffered center-aligned PWM
- **KBI** 4-pin keyboard interrupt module with software selectable polarity on edge or edge/level modes

## Input/Output

- Four General-purpose input/output (I/O) pins, one input-only pin and one output-only pin. Outputs 10 mA each, 60 mA maximum for package.
- Software selectable pullups on ports when used as input
- Software selectable slew rate control and drive strength on ports when used as output
- Internal pullup on RESET and IRQ pin to reduce customer system cost

### **Development Support**

• Single-wire background debug interface

### **Package Options**

- 8-pin SOIC package
- 8-pin PDIP (Only for MC9S08QD4 and MC9S08QD2)
- All package options are RoHS compliant



# **Revision History**

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#### http://freescale.com/

The following revision history table summarizes changes contained in this document.

Revision Number	Revision Date	Description of Changes
1	15 Sep 06	Initial public release
2	09 Jan 07	Added MC9S08QD2 information; added "M" temperature range (-40 °C to 125 °C); updated temperature sensor equation in the ADC chapter.
3	19 Nov. 07	Added S9S08QD4 and S9S08QD2 information for automotive applications. Revised "Accessing (read or write) any flash control register" to "Writing any flash control register" in Section 4.5.5, "Access Errors."
4	9 Sep 08	Changed the SPMSC3 in Section 5.6, "Low-Voltage Detect (LVD) System," and Section 5.6.4, "Low-Voltage Warning (LVW)," to SPMSC2. Added $V_{POR}$ to Table A-5. Updated "How to Reach Us" information.
5	24 Nov 08	Revised dc injection current in Table A-5.
6	14 Oct 10	Added T <sub>JMax</sub> in the Table A-2.

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MC9S08QD4 Series MCU Data Sheet, Rev. 6



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#### Chapter 2 External Signal Description

Although the BKGD pin is a pseudo open-drain pin, the background debug communication protocol provides brief, actively driven, high speedup pulses to ensure fast rise times. Small capacitances from cables and the absolute value of the internal pullup device play almost no role in determining rise and fall times on the BKGD pin.

## 2.2.5 General-Purpose I/O and Peripheral Ports

The MC9S08QD4 series of MCUs support up to 4 general-purpose I/O pins, 1 input-only pin and 1 output-only pin, which are shared with on-chip peripheral functions (timers, serial I/O, ADC, keyboard interrupts, etc.). On each of the MC9S08QD4 series devices there is one input-only and one output-only port pin.

When a port pin is configured as a general-purpose output or a peripheral uses the port pin as an output, software can select one of two drive strengths and enable or disable slew rate control. When a port pin is configured as a general-purpose input or a peripheral uses the port pin as an input, software can enable a pullup device.

For information about controlling these pins as general-purpose I/O pins, see the Chapter 6, "Parallel Input/Output Control." For information about how and when on-chip peripheral systems use these pins, see the appropriate chapter referenced in Table 2-1.

Immediately after reset, all pins that are not output-only are configured as high-impedance, general-purpose inputs with internal pullup devices disabled. After reset, the output-only port function is not enabled but is configured for low output drive strength with slew rate control enabled. The PTA4 pin defaults to BKGD/MS on any reset.

#### NOTE

To avoid extra current drain from floating input pins, the reset initialization routine in the application program must either enable on-chip pullup devices or change the direction of unused pins to outputs so the pins do not float.

## 2.2.5.1 Pin Control Registers

To select drive strength or enable slew rate control or pullup devices, the user writes to the appropriate pin control register located in the high-page register block of the memory map. The pin control registers operate independently of the parallel I/O registers and allow control of a port on an individual pin basis.

## 2.2.5.1.1 Internal Pullup Enable

An internal pullup device can be enabled for each port pin by setting the corresponding bit in one of the pullup enable registers (PTxPEn). The pullup device is disabled if the pin is configured as an output by the parallel I/O control logic or any shared peripheral function, regardless of the state of the corresponding pullup enable register bit. The pullup device is also disabled if the pin is controlled by an analog function.

The KBI module and IRQ function when enabled for rising edge detection causes an enabled internal pull device to be configured as a pulldown.



Chapter 4 Memory Map and Register Definition

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0xFFAA – 0xFFAC	Reserved	_	_	_	_	_	_	_	_
0xFFAD	Reserved for ADCRL of AD26 value during ICS trim	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	ADR0
0xFFAE	Reserved for ADCRH of AD26 value during ICS trim and ICS Trim value "FTRIM"	ADR9	ADR8	_	_	_	_	_	FTRIM
0xFFAF	Reserved for ICS Trim value "TRIM"	TRIM							
0xFFB0 – 0xFFB7	NVBACKKEY	8-Byte Comparison Key							
0xFFB8 – 0xFFBC	Reserved		_	_	_	_	_	_	_
0xFFBD	NVPROT	FPS FPDIS							FPDIS
0xFFBE	Unused	_	_	_	_	_	_	_	_
0xFFBF	NVOPT	KEYEN	FNORED	0	0	0	0	SEC01	SEC00

Table 4-4. Nonvolatile Register Summary

Provided the key enable (KEYEN) bit is 1, the 8-byte comparison key can be used to temporarily disengage memory security. This key mechanism can be accessed only through user code running in secure memory. (A security key cannot be entered directly through background debug commands.) This security key can be disabled completely by programming the KEYEN bit to 0. If the security key is disabled, the only way to disengage security is by mass erasing the flash if needed (normally through the background debug interface) and verifying that flash is blank. To avoid returning to secure mode after the next reset, program the security bits (SEC01:SEC00) to the unsecured state (1:0).

The ICS factory-trimmed value will be stored in 0xFFAE (bit-0) and 0xFFAF. Development tools, such as programmers can trim the ICS and the internal temperature sensor (via the ADC) and store the values in 0xFFAD–0xFFAF.

## 4.4 RAM

The MC9S08QD4 series includes static RAM. The locations in RAM below 0x0100 can be accessed using the more efficient direct addressing mode, and any single bit in this area can be accessed with the bit manipulation instructions (BCLR, BSET, BRCLR, and BRSET). Locating the most frequently accessed program variables in this area of RAM is preferred.

The RAM retains data when the MCU is in low-power wait, stop2, or stop3 mode. At power-on or after wakeup from stop1, the contents of RAM are uninitialized. RAM data is unaffected by any reset provided that the supply voltage does not drop below the minimum value for RAM retention ( $V_{RAM}$ ).



#### **Chapter 4 Memory Map and Register Definition**

program command is issued, the charge pump is enabled and then remains enabled after completion of the burst program operation if these two conditions are met:

- The next burst program command has been queued before the current program operation has completed.
- The next sequential address selects a byte on the same physical row as the current byte being programmed. A row of flash memory consists of 64 bytes. A byte within a row is selected by addresses A5 through A0. A new row begins when addresses A5 through A0 are all 0s.

The first byte of a series of sequential bytes being programmed in burst mode will take the same amount of time to program as a byte programmed in standard mode. Subsequent bytes will program in the burst program time provided that the conditions above are met. In the case the next sequential address is the beginning of a new row, the program time for that byte will be the standard time instead of the burst time. This is because the high voltage to the array must be disabled and then enabled again. If a new burst command has not been queued before the current command completes, then the charge pump will be disabled and high voltage removed from the array.



## 5.8.4 System Options Register 1 (SOPT1)

This high-page register is a write-once register so only the first write after reset is honored. It can be read at any time. Any subsequent attempt to write to SOPT1 (intentionally or unintentionally) is ignored to avoid accidental changes to these sensitive settings. SOPT1 must be written during the user's reset initialization program to set the desired controls even if the desired settings are the same as the reset settings.

	7	6	5	4 <sup>1</sup>	3	2	1	0
R		COPT	STORE		0	0	PKODDE	DOTDE
W	COPE	COPT	SIOPE				DRGDFE	NOIFE
Reset:	1	1	0	1	0	0	1	U
POR:	1	1	0	1	0	0	1	0
		= Unimplemer	nted or Reserve	ed		U = unaffected	I	

<sup>1</sup> Bit 4 is reserved, writes will change the value but will have no effect on this MCU.

#### Figure 5-5. System Options Register 1 (SOPT1)

#### Table 5-6. SOPT1 Register Field Descriptions

Field	Description
7 COPE	<ul> <li>COP Watchdog Enable — This write-once bit selects whether the COP watchdog is enabled.</li> <li>0 COP watchdog timer disabled.</li> <li>1 COP watchdog timer enabled (force reset on timeout).</li> </ul>
6 COPT	<ul> <li>COP Watchdog Timeout — This write-once bit selects the timeout period of the COP. COPT along with COPCLKS in SOPT2 defines the COP timeout period.</li> <li>0 Short timeout period selected.</li> <li>1 Long timeout period selected.</li> </ul>
5 STOPE	<ul> <li>Stop Mode Enable — This write-once bit is used to enable stop mode. If stop mode is disabled and a user program attempts to execute a STOP instruction, an illegal opcode reset is forced.</li> <li>0 Stop mode disabled.</li> <li>1 Stop mode enabled.</li> </ul>
1 BKGDPE	<ul> <li>Background Debug Mode Pin Enable — This write-once bit when set enables the</li> <li>PTA4/TPM2CH0O/BKGD/MS pin to function as BKGD/MS. When clear, the pin functions as one of its output only alternative functions. This pin defaults to the BKGD/MS function following any MCU reset.</li> <li>PTA4/TPM2CH0O/BKGD/MS pin functions as PTA4 or TPM2CH0O.</li> <li>PTA4/TPM2CH0O/BKGD/MS pin functions as BKGD/MS.</li> </ul>
0 RSTPE	<b>RESET</b> Pin Enable — This write-once bit when set enables the PTA5/TPM2CH0I/IRQ/RESET pin to function as RESET. When clear, the pin functions as one of its input only alternative functions. This pin defaults to its input-only port function following an MCU POR. When RSTPE is set, an internal pullup device is enabled on RESET.         0       PTA5/TPM2CH0I/IRQ/RESET pin functions as PTA5, IRQ or TPM2CH0I.         1       PTA5/TPM2CH0I/IRQ/RESET pin functions as RESET.

Chapter 5 Resets, Interrupts, and General System Control

RTIS2:RTIS1:RTIS0	Using Internal 1 kHz Clock Source <sup>1 2</sup>	Using 32 kHz ICS Clock Source Period = $t_{ext}^3$
0:0:0	Disable RTI	Disable RTI
0:0:1	8 ms	$t_{ext}  imes 256$
0:1:0	32 ms	$t_{ext}  imes 1024$
0:1:1	64 ms	$t_{ext}  imes 2048$
1:0:0	128 ms	$t_{ext}  imes 4096$
1:0:1	256 ms	$t_{ext} \times 8192$
1:1:0	512 ms	t <sub>ext</sub> × 16384
1:1:1	1.024 s	t <sub>ext</sub> × 32768

#### Table 5-11. Real-Time Interrupt Period

<sup>1</sup> Values are shown in this column based on t<sub>RTI</sub> = 1 ms. See t<sub>RTI</sub> in the Section A.8.1, "Control Timing," for the tolerance of this value.

<sup>2</sup> The initial RTI timeout period will be up to one 1 kHz clock period less than the time specified.

 $^{3}$  t<sub>ext</sub> is the period of the 32 kHz ICS frequency.

# 5.8.8 System Power Management Status and Control 1 Register (SPMSC1)

This high-page register contains status and control bits to support the low voltage detect function, and to enable the bandgap voltage reference for use by the ADC module. To configure the low voltage detect trip voltage, see Table 5-13 for the LVDV bit description in SPMSC2.



<sup>1</sup> Bit 1 is a reserved bit that must always be written to 0.

<sup>2</sup> This bit can be written only one time after reset. Additional writes are ignored.

#### Figure 5-10. System Power Management Status and Control 1 Register (SPMSC1)

#### Table 5-12. SPMSC1 Register Field Descriptions

Field	Description
7 LVDF	Low-Voltage Detect Flag — Provided LVDE = 1, this read-only status bit indicates a low-voltage detect event.
6 LVDACK	<b>Low-Voltage Detect Acknowledge</b> — This write-only bit is used to acknowledge low voltage detection errors (write 1 to clear LVDF). Reads always return 0.



## 6.4.2.1 Port A Internal Pullup Enable (PTAPE)

An internal pullup device can be enabled for each port pin by setting the corresponding bit in the pullup enable register (PTAPEn). The pullup device is disabled if the pin is configured as an output by the parallel I/O control logic or any shared peripheral function regardless of the state of the corresponding pullup enable register bit. The pullup device is also disabled if the pin is controlled by an analog function.

_	7	6	5	4	3	2	1	0
R	0	0		ρταρεμ <sup>1</sup>	ρτάρες	ΡΤΔΡΕ2		ρτάρεο
W								
Reset:	0	0	0	0	0	0	0	0

<sup>1</sup> PTAPE4 has no effect on the output-only PTA4 pin.

#### Figure 6-4. Internal Pullup Enable for Port A Register (PTAPE)

#### Table 6-3. PTAPE Register Field Descriptions

Field	Description
5:0	Internal Pullup Enable for Port A Bits — Each of these control bits determines if the internal pullup device is
PTAPE[5:0]	enabled for the associated PTA pin. For port A pins that are configured as outputs, these bits have no effect and
	the internal pullup devices are disabled.
	0 Internal pullup device disabled for port A bit n.
	1 Internal pullup device enabled for port A bit n.

## 6.4.2.2 Port A Slew Rate Enable (PTASE)

Slew rate control can be enabled for each port pin by setting the corresponding bit in the slew rate control register (PTASEn). When enabled, slew control limits the rate at which an output can transition in order to reduce EMC emissions. Slew rate control has no effect on pins which are configured as inputs.

	7	6	5	4	3	2	1	0
R	0	0		DTAGEA	DTAGES	DTAGE2		DTASEO
w			T IAGES		TIAGES	TIAGEZ	TIAGET	I IAGEO
Reset:	0	0	1	1	1	1	1	1

<sup>1</sup> PTASE5 has no effect on the input-only PTA5 pin.

#### Figure 6-5. Slew Rate Enable for Port A Register (PTASE)

#### Table 6-4. PTASE Register Field Descriptions

Field	Description
5:0 PTASE[5:0]	<ul> <li>Output Slew Rate Enable for Port A Bits — Each of these control bits determines if the output slew rate control is enabled for the associated PTA pin. For port A pins that are configured as inputs, these bits have no effect.</li> <li>Output slew rate control disabled for port A bit n.</li> <li>Output slew rate control enabled for port A bit n.</li> </ul>

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Chapter 7 Central Processor Unit (S08CPUV2)

## 7.2 Programmer's Model and CPU Registers

Figure 7-1 shows the five CPU registers. CPU registers are not part of the memory map.



Figure 7-1. CPU Registers

## 7.2.1 Accumulator (A)

The A accumulator is a general-purpose 8-bit register. One operand input to the arithmetic logic unit (ALU) is connected to the accumulator and the ALU results are often stored into the A accumulator after arithmetic and logical operations. The accumulator can be loaded from memory using various addressing modes to specify the address where the loaded data comes from, or the contents of A can be stored to memory using various addressing modes to specify the address where the specify the address where data from A will be stored.

Reset has no effect on the contents of the A accumulator.

## 7.2.2 Index Register (H:X)

This 16-bit register is actually two separate 8-bit registers (H and X), which often work together as a 16-bit address pointer where H holds the upper byte of an address and X holds the lower byte of the address. All indexed addressing mode instructions use the full 16-bit value in H:X as an index reference pointer; however, for compatibility with the earlier M68HC05 Family, some instructions operate only on the low-order 8-bit half (X).

Many instructions treat X as a second general-purpose 8-bit register that can be used to hold 8-bit data values. X can be cleared, incremented, decremented, complemented, negated, shifted, or rotated. Transfer instructions allow data to be transferred from A or transferred to A where arithmetic and logical operations can then be performed.

For compatibility with the earlier M68HC05 Family, H is forced to 0x00 during reset. Reset has no effect on the contents of X.





## 7.3.6.7 SP-Relative, 16-Bit Offset (SP2)

This variation of indexed addressing uses the 16-bit value in the stack pointer (SP) plus a 16-bit offset included in the instruction as the address of the operand needed to complete the instruction.

## 7.4 Special Operations

The CPU performs a few special operations that are similar to instructions but do not have opcodes like other CPU instructions. In addition, a few instructions such as STOP and WAIT directly affect other MCU circuitry. This section provides additional information about these operations.

## 7.4.1 Reset Sequence

Reset can be caused by a power-on-reset (POR) event, internal conditions such as the COP (computer operating properly) watchdog, or by assertion of an external active-low reset pin. When a reset event occurs, the CPU immediately stops whatever it is doing (the MCU does not wait for an instruction boundary before responding to a reset event). For a more detailed discussion about how the MCU recognizes resets and determines the source, refer to the Resets, Interrupts, and System Configuration chapter.

The reset event is considered concluded when the sequence to determine whether the reset came from an internal source is done and when the reset pin is no longer asserted. At the conclusion of a reset event, the CPU performs a 6-cycle sequence to fetch the reset vector from 0xFFFE and 0xFFFF and to fill the instruction queue in preparation for execution of the first program instruction.

## 7.4.2 Interrupt Sequence

When an interrupt is requested, the CPU completes the current instruction before responding to the interrupt. At this point, the program counter is pointing at the start of the next instruction, which is where the CPU should return after servicing the interrupt. The CPU responds to an interrupt by performing the same sequence of operations as for a software interrupt (SWI) instruction, except the address used for the vector fetch is determined by the highest priority interrupt that is pending when the interrupt sequence started.

The CPU sequence for an interrupt is:

- 1. Store the contents of PCL, PCH, X, A, and CCR on the stack, in that order.
- 2. Set the I bit in the CCR.
- 3. Fetch the high-order half of the interrupt vector.
- 4. Fetch the low-order half of the interrupt vector.
- 5. Delay for one free bus cycle.
- 6. Fetch three bytes of program information starting at the address indicated by the interrupt vector to fill the instruction queue in preparation for execution of the first instruction in the interrupt service routine.

After the CCR contents are pushed onto the stack, the I bit in the CCR is set to prevent other interrupts while in the interrupt service routine. Although it is possible to clear the I bit with an instruction in the



## 7.4.5 BGND Instruction

The BGND instruction is new to the HCS08 compared to the M68HC08. BGND would not be used in normal user programs because it forces the CPU to stop processing user instructions and enter the active background mode. The only way to resume execution of the user program is through reset or by a host debug system issuing a GO, TRACE1, or TAGGO serial command through the background debug interface.

Software-based breakpoints can be set by replacing an opcode at the desired breakpoint address with the BGND opcode. When the program reaches this breakpoint address, the CPU is forced to active background mode rather than continuing the user program.



Figure 8-10. Configuration Register (ADCCFG)

### Table 8-5. ADCCFG Register Field Descriptions

Field	Description
7 ADLPC	<ul> <li>Low Power Configuration — ADLPC controls the speed and power configuration of the successive approximation converter. This is used to optimize power consumption when higher sample rates are not required.</li> <li>0 High speed configuration</li> <li>1 Low power configuration: {FC31}The power is reduced at the expense of maximum clock speed.</li> </ul>
6:5 ADIV	<b>Clock Divide Select</b> — ADIV select the divide ratio used by the ADC to generate the internal clock ADCK. Table 8-6 shows the available clock configurations.
4 ADLSMP	<ul> <li>Long Sample Time Configuration — ADLSMP selects between long and short sample time. This adjusts the sample period to allow higher impedance inputs to be accurately sampled or to maximize conversion speed for lower impedance inputs. Longer sample times can also be used to lower overall power consumption when continuous conversions are enabled if high conversion rates are not required.</li> <li>Short sample time</li> <li>Long sample time</li> </ul>
3:2 MODE	<b>Conversion Mode Selection</b> — MODE bits are used to select between 10- or 8-bit operation. See Table 8-7.
1:0 ADICLK	<b>Input Clock Select</b> — ADICLK bits select the input clock source to generate the internal clock ADCK. See Table 8-8.

#### Table 8-6. Clock Divide Select

ADIV	Divide Ratio	Clock Rate
00	1	Input clock
01	2	Input clock ÷ 2
10	4	Input clock ÷ 4
11	8	Input clock ÷ 8

#### Table 8-7. Conversion Modes

MODE	Mode Description
00	8-bit conversion (N=8)
01	Reserved
10	10-bit conversion (N=10)
11	Reserved



## 9.4.4 Low Power Bit Usage

The low power bit (LP) is provided to allow the FLL to be disabled and thus conserve power when it is not being used. However, in some applications it may be desirable to enable the FLL and allow it to lock for maximum accuracy before switching to an FLL engaged mode. Do this by writing the LP bit to 0.

## 9.4.5 Internal Reference Clock

When IRCLKEN is set the internal reference clock signal will be presented as ICSIRCLK, which can be used as an additional clock source. The ICSIRCLK frequency can be re-targeted by trimming the period of the internal reference clock. This can be done by writing a new value to the TRIM bits in the ICSTRM register. Writing a larger value will slow down the ICSIRCLK frequency, and writing a smaller value to the ICSTRM register will speed up the ICSIRCLK frequency. The TRIM bits will effect the ICSOUT frequency if the ICS is in FLL engaged internal (FEI), FLL bypassed internal (FBI), or FLL bypassed internal low power (FBILP) mode. The TRIM and FTRIM value will not be affected by a reset.

Until ICSIRCLK is trimmed, programming low reference divider (RDIV) factors may result in ICSOUT frequencies that exceed the maximum chip-level frequency and violate the chip-level clock timing specifications (see the Device Overview chapter).

If IREFSTEN is set and the IRCLKEN bit is written to 1, the internal reference clock will keep running during stop mode in order to provide a fast recovery upon exiting stop.

All MCU devices are factory programmed with a trim value in a reserved memory location. This value can be copied to the ICSTRM register during reset initialization. The factory trim value does not include the FTRIM bit. For finer precision, the user can trim the internal oscillator in the application and set the FTRIM bit accordingly.

## 9.4.6 Optional External Reference Clock

The ICS module can support an external reference clock with frequencies between 31.25 kHz to 5 MHz in all modes. When the ERCLKEN is set, the external reference clock signal will be presented as ICSERCLK, which can be used as an additional clock source. When IREFS = 1, the external reference clock will not be used by the FLL and will only be used as ICSERCLK. In these modes, the frequency can be equal to the maximum frequency the chip-level timing specifications will support (see the Device Overview chapter).

If EREFSTEN is set and the ERCLKEN bit is written to 1, the external reference clock will keep running during stop mode in order to provide a fast recovery upon exiting stop.



# Chapter 11 Timer/Pulse-Width Modulator (S08TPMV2)

## 11.1 Introduction

Figure 11-1 shows the MC9S08QD4 series block diagram with the TPM module and pins highlighted.

## 11.1.1 TPM2 Configuration Information

The TPM2 module consist of a single channel, TPM2CH0, that is multiplexed with input pin PTA4 and output pin PTA5. When TPM2 is configured for input capture, the TPM2CH0 will connect to the PTA5 (TPM2CH0I). When TPM2 is configured for output compare, the TPM2CH0 will connect to the PTA4 (TPM2CH0O). When TPM2 is disabled, PTA4 and PTA5 function as standard port pins.

## 11.1.2 TCLK1 and TCLK2 Configuration Information

The TCLK1 and TCLK2 are the external clock source inputs for TPM1 and TPM2 respectively.



#### Timer/Pulse-Width Modulator (S08TPMV2)

Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

## 11.3.1 Timer Status and Control Register (TPMxSC)

TPMxSC contains the overflow status flag and control bits that are used to configure the interrupt enable, TPM configuration, clock source, and prescale divisor. These controls relate to all channels within this timer module.

	7	6	5	4	3	2	1	0
R W	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
Reset	0	0	0	0	0	0	0	0
	= Unimplemented or Reserved							



Table 11-1. TPMXSC Register Field Descriptions	Table 11-1.	TPMxSC	Register	Field	Descriptions
--	-------------	--------	----------	-------	--------------

Field	Description
7 TOF	<b>Timer Overflow Flag</b> — This flag is set when the TPM counter changes to 0x0000 after reaching the modulo value programmed in the TPM counter modulo registers. When the TPM is configured for CPWM, TOF is set after the counter has reached the value in the modulo register, at the transition to the next lower count value. Clear TOF by reading the TPM status and control register when TOF is set and then writing a 0 to TOF. If another TPM overflow occurs before the clearing sequence is complete, the sequence is reset so TOF would remain set after the clear sequence was completed for the earlier TOF. Reset clears TOF. Writing a 1 to TOF has no effect. 0 TPM counter has not reached modulo value or overflow 1 TPM counter has overflowed
6 TOIE	<ul> <li>Timer Overflow Interrupt Enable — This read/write bit enables TPM overflow interrupts. If TOIE is set, an interrupt is generated when TOF equals 1. Reset clears TOIE.</li> <li>0 TOF interrupts inhibited (use software polling)</li> <li>1 TOF interrupts enabled</li> </ul>
5 CPWMS	<ul> <li>Center-Aligned PWM Select — This read/write bit selects CPWM operating mode. Reset clears this bit so the TPM operates in up-counting mode for input capture, output compare, and edge-aligned PWM functions. Setting CPWMS reconfigures the TPM to operate in up-/down-counting mode for CPWM functions. Reset clears CPWMS.</li> <li>0 All TPMx channels operate as input capture, output compare, or edge-aligned PWM mode as selected by the MSnB:MSnA control bits in each channel's status and control register</li> <li>1 All TPMx channels operate in center-aligned PWM mode</li> </ul>
4:3 CLKS[B:A]	<b>Clock Source Select</b> — As shown in Table 11-2, this 2-bit field is used to disable the TPM system or select one of three clock sources to drive the counter prescaler. The external source and the XCLK are synchronized to the bus clock by an on-chip synchronization circuit.
2:0 PS[2:0]	<b>Prescale Divisor Select</b> — This 3-bit field selects one of eight divisors for the TPM clock input as shown in Table 11-3. This prescaler is located after any clock source synchronization or clock source selection, so it affects whatever clock source is selected to drive the TPM system.





Figure A-3. Typical Low-Side Driver (Sink) Characteristics High Drive (PTxDSn = 1),  $V_{DD}$  = 5.0 V,  $V_{OL}$  vs.  $I_{OL}$ 



Figure A-4. Typical Low-Side Driver (Sink) Characteristics High Drive (PTxDSn = 1),  $V_{DD}$  = 3.0 V,  $V_{OL}$  vs.  $I_{OL}$ 





Figure A-13. IRQ/KBIPx Timing

## A.8.2 Timer/PWM (TPM) Module Timing

Synchronizer circuits determine the shortest input pulses that can be recognized or the fastest clock that can be used as the optional external source to the timer counter. These synchronizers operate from the current bus rate clock.

Function	Symbol	Min	Max	Unit
External clock frequency	f <sub>TCLK</sub>	dc	f <sub>Bus</sub> /4	MHz
External clock period	t <sub>TCLK</sub>	4	_	t <sub>cyc</sub>
External clock high time	t <sub>clkh</sub>	1.5	_	t <sub>cyc</sub>
External clock low time	t <sub>clkl</sub>	1.5	_	t <sub>cyc</sub>
Input capture pulse width	t <sub>ICPW</sub>	1.5	_	t <sub>cyc</sub>

Table A-9. TPM/MTIM Input Timing



Figure A-14. Timer External Clock

![](_page_19_Figure_10.jpeg)

Figure A-15. Timer Input Capture Pulse

![](_page_20_Picture_0.jpeg)

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994.
- 2. ALL DIMENSIONS ARE IN INCHES.
- 3. 626-03 TO 626-06 OBSOLETE. NEW STANDARD 626-07.
- $\triangle$  DIMENSION TO CENTER OF LEAD WHEN FORMED PARALLEL.
- A PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CONERS). STYLE 1:

PIN	1.	AC	ΙN	
	2.	DC	+ IN	
	З.	DC	— IN	
	4.	AC	ΙN	

- 5. GROUND
- OUTPUT
   AUXILIARY
- 8. VCC

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TITLE:		DOCUMENT NO	): 98ASB42420B	REV: N
8 LD PDIP		CASE NUMBER	8: 626–06	19 MAY 2005
		STANDARD: NO	N-JEDEC	